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1. Name of Party(ies) conveying an interest: Hichem Abdallah Jurgen Ohm Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No	2. Name and Address of Party(ies) receiving an interest: Name: Infineon Technologies AG Internal Address: Street Address: St. Martin, Str. 53, 81669 City: Munich State/Zip: Germany Additional name(s) and addresses attached? ☐ Yes ☒ No

3. Description of the interest conveyed:

☒ Assignment ☐ Change of Name Other:

☐ Security Agreement ☐ Merger

Execution Date: Abdallah 11/19/04; Ohm 11/13/04

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FINANCE SECTION

4. Application number(s) or patent number(s).

If this document is being filed together with a new application, the execution date of the application is: ______ Date

A. Patent Application No.(s)
10/511,189

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed: BRINKS HOFER GILSON & LIONE P.O. BOX 10395 CHICAGO, IL 60610 (312)321-4200	6. Number of applications and patents involved: 1 7. Total fee (37 CFR 3.41) $ 40.00 ☒ Enclosed ☐ Authorized to be charged to Deposit Account No. 23-1925 8. ☒ Please charge any deficiencies in fee or credit any overpayment to Deposit Account No. 23-1925.

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9. Statement and signature.
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Scott W. Brim
Name of Person Signing

S. W. B
Signature

December 1, 2004
Date

Total number of pages including cover sheet, attachments, and document: 2

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INFINEON REF NO. I0353US/mgl/pp
O.C. REF NO. 10808/170

ASSIGNMENT

For good and valuable consideration, I, Hichem ABDALLAH, a citizen of Germany, residing at Marsiliusstr. 28, D-50937 Köln, Germany, and Jürgen ÖHM, a citizen of Germany, residing at Ina-Seidel-Str. 74, D-40885 Ratingen, Germany, hereinafter individually or collectively referred to as "Assignor";

Hereby sell, assign and transfer to **Infineon Technologies AG**, a corporation organized and existing under the laws of Germany, having its principal place of business at St.-Martin-Str. 53, 81669 Munich, Germany, hereinafter "Assignee", its successors, assigns and legal representatives, the entire right, title and interest in and for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned and

filed on April 17, 2003 International Serial No. PCT/DE03/01304,

submitted on October 12, 2004 U.S. Serial No. 10/511,189,

entitled: **SEMICONDUCTOR COMPONENT WITH INTEGRATED CAPACITANCE STRUCTURE HAVING A PLURALITY OF METALLIZATION PLANES**

and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on said improvements;

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and legal representatives, all facts known to the undersigned relating to said improvements an the history thereof; and generally do everything possible which said Assignee, its successors, assigns or legal representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, it successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

SIGNATURE: ______________________ DATE: Nov. 19. 2004
Hichem ABDALLAH

SIGNATURE: ______________________ DATE: Nov. 13, 2004
Jürgen ÖHM